

	Type	Hits	Search Text	DBs
1	BRS	5	4781969.pn. or 5073840.pn. or 5770032.pn. or 5817535.pn. or 5858815.pn.	USPAT; JPO
2	BRS	1	"3868724".PN.	USPAT
3	BRS	1	"4878098".PN.	USPAT
4	BRS	1	"4884122".PN.	USPAT
5	BRS	1	"4967261".PN.	USPAT
6	BRS	1	"4967261".PN.	USPAT
7	BRS	1	"5148265".PN.	USPAT
8	BRS	1	"5148266".PN.	USPAT
9	BRS	1	"5258330".PN.	USPAT
10	BRS	1	"5346861".PN.	USPAT
11	BRS	1	"5347159".PN.	USPAT
12	BRS	1	"5390844".PN.	USPAT
13	BRS	1	"5398863".PN.	USPAT
14	BRS	1	"5414298".PN.	USPAT
15	BRS	1	"5455390".PN.	USPAT
16	BRS	1	"5477611".PN.	USPAT
17	BRS	1	"5489749".PN.	USPAT
18	BRS	1	"5491302".PN.	USPAT
19	BRS	1	"5518964".PN.	USPAT
20	BRS	30901	(chip or die or semiconductor) and substrate and silder adj mask and wire (copper or "Cu") and heat adj (sink or dissipat\$ or spreader or transfer)	USPAT; JPO

	Type	Hits	Search Text	DBs
21	BRS	179	(chip or die or semiconductor) and substrate and solder adj mask and wire and (copper or "Cu") and heat adj (sink or dissipat\$ or spreader or transfer)	USPAT; JPO
22	BRS	75	(257/690 or 257/706 or 257/707 or 257/720 or 257/778) and (chip or die or semiconductor) and substrate and solder adj mask and wire and (copper or "Cu") and heat adj (sink or dissipat\$ or spreader or transfer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
23	BRS	79	(257/690 or 257/706 or 257/707 or 257/720 or 257/778) and (chip or die or semiconductor) and solder adj mask and wire and (copper or "Cu") and heat adj (sink or dissipat\$ or spreader or transfer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
24	BRS	901	(257/690 or 257/706 or 257/707 or 257/720 or 257/778) and (chip or die or semiconductor) and wire and (copper or "Cu") and heat adj (sink or dissipat\$ or spreader or transfer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
25	BRS	1	"4951123".PN.	USPAT
26	BRS	1	"5155067".PN.	USPAT
27	BRS	1	"5677566".PN.	USPAT
28	BRS	1	"5696033".PN.	USPAT
29	BRS	1	"5736456".PN.	USPAT
30	BRS	1	"5739585".PN.	USPAT
31	BRS	1	"5789803".PN.	USPAT
32	BRS	1	"5817535".PN.	USPAT
33	BRS	1	"5849635".PN.	USPAT

	Type	Hits	Search Text	DBs
34	BRS	1	"5895967".PN.	USPAT
35	BRS	1	"6060774".PN.	USPAT
36	BRS	1	"6091140".PN.	USPAT
37	BRS	408	(257/779 or 257/780 or 257/782 or 257/783 or 257/784 or 257/786) and (chip or die or semiconductor) and wire and (copper or "Cu") and heat adj (sink or dissipat\$ or spreader or transfer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
38	BRS	49	(257/779 or 257/780 or 257/782 or 257/783 or 257/784 or 257/786) and (chip or die or semiconductor) and wire and (copper or "Cu") adj plate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
39	BRS	59	(257/779 or 257/780 or 257/782 or 257/783 or 257/784 or 257/786) and (chip or die or semiconductor) and (copper or "Cu") adj plate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
40	BRS	0	257//\$.ccls. and (chip or die or semiconductor) and (copper or "Cu") adj (plate or layer or plane) and via	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
41	BRS	0	257//\$.ccls. and (chip or die or semiconductor) and (copper or "Cu") and ground adj (plate or layer or plane) and via	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
42	BRS	589	257/\$.ccls. and (chip or die or semiconductor) and (copper or "Cu") and ground adj (plate or layer or plane) and via	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
43	BRS	448	361/\$.ccls. and (chip or die or semiconductor) and (copper or "Cu") and ground adj (plate or layer or plane) and via	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB

	Type	Hits	Search Text	DBs
44	BRS	213	438/\$.ccls. and (chip or die or semiconductor) and (copper or "Cu") and ground adj (plate or layer or plane) and via	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
45	BRS	0	((Alan near G. near Wood) or (Larry near D. near Kinsman)) and (chip or die or semiconductor) and (copper or "Cu") and ground adj (plate or layer or plane) and via	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
46	BRS	0	((Alan near G. near Wood) or (Larry near D. near Kinsman)) and (chip or die or semiconductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
47	BRS	0	((Alan near G. near Wood) or (Larry near D. near Kinsman))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
48	BRS	272	((Alan near Wood) or (Larry near D. near Kinsman))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
49	BRS	373	((Alan near Wood) or (Larry near Kinsman))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
50	BRS	181	(chip or die or semiconductor) and wire and (copper or "Cu") and heat adj (sink or dissipat\$ or spreader or transfer)	JPO
51	BRS	5	(chip or die or semiconductor) and wire and (copper or "Cu") and heat adj (sink or dissipat\$ or spreader or transfer) and ball	JPO
52	BRS	11	5858815.pn. or 5696033.pn. or 03227042.pn. or 5834839.pn. or 5784260.pn. or 6326700.pn. or 6048755.pn. or 5366906.pn. or 6287942.pn. or 5384691.pn. or 6268650.pn.	USPAT; JPO

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53	BRS	7	5858815.pn. or 5696033.pn. or 03227042.pn. or 5834839.pn. or 6326700.pn. or 5366906.pn. or 6268650.pn.	USPAT; JPO
54	BRS	44	(chip or die or semiconductor) and wire and (copper or "Cu") and heat adj (sink or dissipat\$ or spreader or transfer) and ball and via and ground adj (plate or layer or film)	USPAT; JPO
55	BRS	446	(chip or die or semiconductor) and wire and (copper or "Cu") and heat adj (sink or dissipat\$ or spreader or transfer) and ball and via and ground	USPAT; JPO
56	BRS	7	(chip or die or semiconductor) and wire and (copper or "Cu") and heat adj (sink or dissipat\$ or spreader or transfer) near ground and ball and via	USPAT; JPO
57	BRS	89	solder adj mask and dielectric adj layer and heat adj sink	USPAT; JPO
58	BRS	1	solder adj mask near dielectric adj layer and heat adj sink	USPAT; JPO
59	BRS	8	5858815.pn. or 5696033.pn. or 03227042.pn. or 5834839.pn. or 6326700.pn. or 6268650.pn. or 6160714.pn. or 5796170.pn.	USPAT; JPO